

## **Application Data Sheet**

### **Application Information**

Application Type:: Regular  
Subject Matter:: Utility  
Title:: Semiconductor multi-package module having wire bond interconnect between stacked packages and having electrical shield  
Attorney Docket Number:: CPAC 1017-4 D2  
Total Drawing Sheets:: 15  
Small Entity?:: No

### **Applicant Information**

Applicant Authority Type: Inventor  
Primary Citizenship Country: US  
Status: Full Capacity  
Given Name: Marcos  
Family Name: Karnezos  
City of Residence: Palo Alto  
State or Province of Residence: CA  
Country of Residence: US  
Street of mailing address: 535 Lytton Avenue  
City of mailing address: Palo Alto  
State or Province of mailing address: CA  
Country of mailing address: US  
Postal or Zip Code of mailing address: 94301

## **Correspondence Information**

Correspondence Customer Number:: 22470

## **Representative Information**

Representative Customer Number::	22470
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## **Domestic Priority Information**

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	An application claiming the benefit under 35 USC 119 (e)	60411590	17 September 2002

## **Assignee Information**

Assignee name:: ChipPAC, Inc.

Street of mailing address:: 47400 Kato Road

City of mailing address:: Fremont

State or Province of mailing address:: CA

Country of mailing address:: US

Postal or Zip Code of mailing address:: 94538